

**APPLICATION DATA SHEET****Application Information**

Application number::

Filing Date::

Application Type:: Regular

Subject Matter:: Utility

Suggested classification::

Suggested Group Art Unit::

CD-ROM or CD-R?:: None

Number of CD disks::

Number of copies of CDs::

Sequence submission?::

Computer Readable Form (CRF)?:: No

Number of copies of CRF::

Title :: PROCESS FOR FORMING A BURIED CAVITY  
IN A SEMICONDUCTOR MATERIAL WAFER  
AND A BURIED CAVITY

Attorney Docket Number:: 854063.618D1

Request for Early Publication?:: No

Request for Non-Publication?:: No

Suggested Drawing Figure::

Total Drawing Sheets:: 3

Small Entity?:: No

Petition included?:: No

Petition Type::

Licensed U.S. Gov't Agency::

Contract or Grant No::

Secrecy Order in Parent Appl.?:: No

**First Applicant Information**

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Italy  
Status:: Full Capacity  
Given Name:: Pietro  
Middle Name::  
Family Name:: Erratico  
Name Suffix::  
City of Residence:: Milano  
State or Province of Residence::  
Country of Residence:: Italy  
Street of mailing address:: Via Sismondi, 6  
City of mailing address:: Milano  
State or Province of mailing address::  
Country of mailing address:: Italy  
Postal or Zip Code of mailing address:: 20133

**Second Applicant Information**

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Italy  
Status:: Full Capacity  
Given Name:: Enrico  
Middle Name::  
Family Name:: Sacchi  
Name Suffix::  
City of Residence:: Pavia  
State or Province of Residence::  
Country of Residence:: Italy  
Street of mailing address:: Via Bixio, 9

City of mailing address:: Pavia  
State or Province of mailing address::  
Country of mailing address:: Italy  
Postal or Zip Code of mailing address:: 27100

### Third Applicant Information

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Italy  
Status:: Full Capacity  
Given Name:: Flavio  
Middle Name::  
Family Name:: Villa  
Name Suffix::  
City of Residence:: Milano  
State or Province of Residence::  
Country of Residence:: Italy  
Street of mailing address:: Via P. Lambertenghi, 23  
City of mailing address:: Milano  
State or Province of mailing address::  
Country of mailing address:: Italy  
Postal or Zip Code of mailing address:: 20159

### Fourth Applicant Information

Applicant Authority Type:: Inventor  
Primary Citizenship Country:: Italy  
Status:: Full Capacity  
Given Name:: Gabriele  
Middle Name::  
Family Name:: Barlocchi

Name Suffix::

City of Residence:: Cornaredo

State or Province of Residence::

Country of Residence:: Italy

Street of mailing address:: Via Lucernate, 8

City of mailing address:: Cornaredo

State or Province of mailing address::

Country of mailing address:: Italy

Postal or Zip Code of mailing address:: 20010

#### **Fifth Applicant Information**

Applicant Authority Type:: Inventor

Primary Citizenship Country:: Italy

Status:: Full Capacity

Given Name:: Pietro

Middle Name::

Family Name:: Corona

Name Suffix::

City of Residence:: Roma

State or Province of Residence::

Country of Residence:: Italy

Street of mailing address:: Via Dei Volsci, 44

City of mailing address:: Roma

State or Province of mailing address::

Country of mailing address:: Italy

Postal or Zip Code of mailing address:: 00185

**Correspondence Information**

Correspondence Customer Number :: **00500**

**Representative Information**

Representative Customer Number::		<b>00500</b>
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**Domestic Priority Information**

Application ::	Continuity Type::	Parent Application::	Parent Filing Date::
This application	Division of	09/797,206	02/27/01

**Foreign Priority Information**

Country::	Application number::	Filing Date::	Priority Claimed::
Europe	00830148.3	02/29/00	Yes

**Assignee Information**

Assignee name::	STMicroelectronics S.r.l.
Street of mailing address::	Via C. Olivetti, 2
City of mailing address::	Agrate Brianza
State or Province of mailing address::	
Country of mailing address::	Italy
Postal or Zip Code of mailing address::	20041

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